



**SDI Review Form 1.6**

Journal Name:	<a href="#">Journal of Materials Science Research and Reviews</a>
Manuscript Number:	<b>Ms_JMSRR_42082</b>
Title of the Manuscript:	<b>The Study of Creep Properties of Sn-5wt%Sb Lead-Free Solders with Annealing Temperature</b>
Type of the Article	<b>Original Research Article</b>

**General guideline for Peer Review process:**

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

**PART 1: Review Comments**

	<b>Reviewer's comment</b>	<b>Author's comment</b> (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments	<b>All my comments are inside the paper</b>	
<b>Minor</b> REVISION comments		
<b>Optional/General</b> comments		

**Reviewer Details:**

Name:	<b>Zakaria Boumerzoug</b>
Department, University & Country	<b>University of Biskra, Algeria</b>